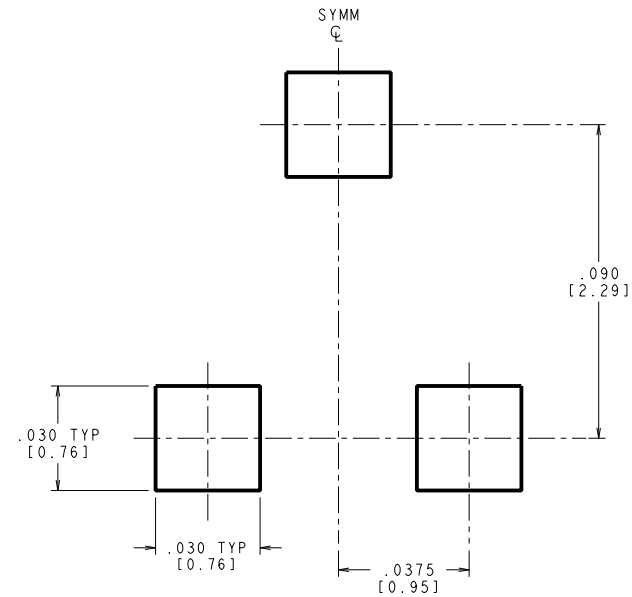
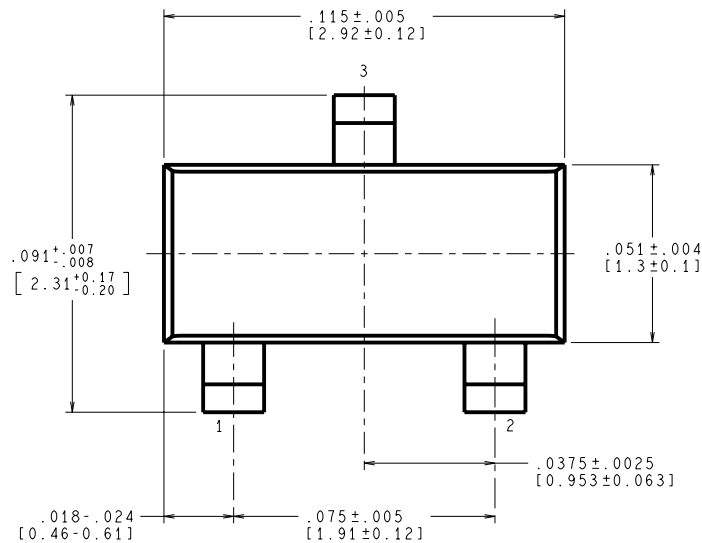
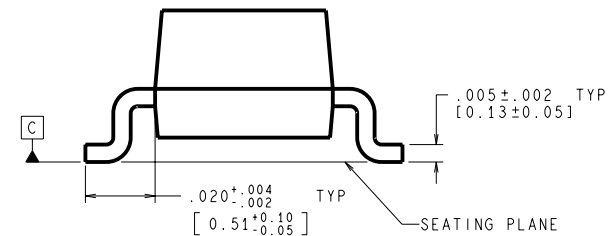
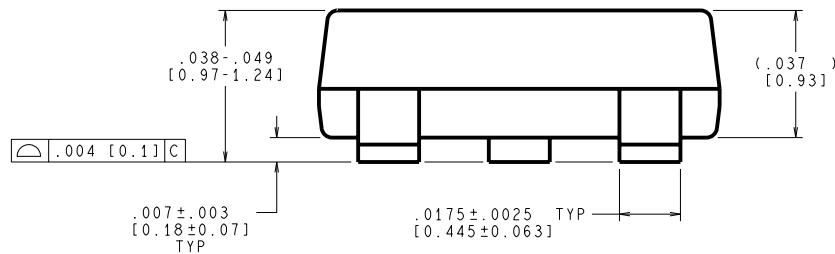


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
F	REVISE & REDRAW PER CURRENT STDS; ADD LAND PATTERN	11205	11/29/95	TL/OM
G	ADD .004[0.1] COPLANARITY; NOTE 1: 200 WAS 150, 5.08 WAS 3.81	11924	02/23/1998	MS/



LAND PATTERN RECOMMENDATION



CONTROLLING DIMENSION IS INCH
VALUES IN () ARE MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH TO BE 200 MICROINCHES/ 5.08 MICROMETERS
MINIMUM TIN/LEAD (SOLDER) ON ALLOY 42.
- JEDEC REGISTRATION TO-236, VARIATION AA, ISSUE G, DATED JUL 1993.

APPROVALS		DATE	 2900 Semiconductor dr., Santa Clara, CA 95052-8090	
DRWN	T. LEQUANG	11/29/95		
DFTG. CHK.			MOLDED, SOT-23, 3 LEAD, HIGH PROFILE	
ENGR. CHK.				
 INCH (MM)		SCALE	SIZE	DRAWING NUMBER
		N/A	C	(SC)MKT-M03A
		DO NOT SCALE DRAWING	REV	G
		SHEET 1 of 1		